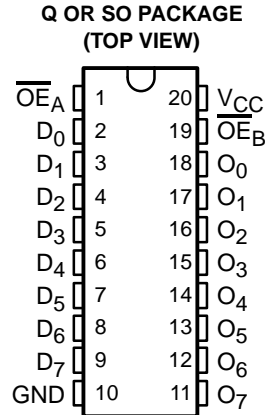


# CY74FCT2541T

## 8-BIT BUFFER/LINE DRIVER WITH 3-STATE OUTPUTS

SCCS041B – SEPTEMBER 1994 – REVISED SEPTEMBER 2001

- Function and Pinout Compatible With FCT and F Logic
- 25-Ω Output Series Resistors to Reduce Transmission-Line Reflection Noise
- Reduced  $V_{OH}$  (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- 12-mA Output Sink Current  
15-mA Output Source Current
- 3-State Outputs



### description

The CY74FCT2541T is an octal buffer and line driver designed to be employed as a memory-address driver, clock driver, and bus-oriented transmitter/receiver. On-chip termination resistors at the outputs reduce system noise caused by reflections. The CY74FCT2541T can replace the CY74FCT541T to reduce noise in an existing design. The speed of the CY74FCT2541T is comparable to bipolar logic counterparts, while reducing power dissipation. Input and output voltage levels allow direct interface with TTL and CMOS devices without external components.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### ORDERING INFORMATION

TA	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QSOP – Q	Tape and reel	4.1	CY74FCT2541CTQCT	FCT2541C
		Tube	4.1	CY74FCT2541CTSOC	FCT2541C
	SOIC – SO	Tape and reel	4.1	CY74FCT2541CTSOCT	
		Tube	4.8	CY74FCT2541ATQCT	FCT2541A
	SOIC – SO	Tape and reel	4.8	CY74FCT2541ATSOCT	FCT2541A
		Tube	8	CY74FCT2541TQCT	FCT2541
	SOIC – SO	Tape and reel	8	CY74FCT2541TSOC	FCT2541
		Tube	8	CY74FCT2541TSOCT	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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CY74FCT2541T  
8-BIT BUFFER/LINE DRIVER  
WITH 3-STATE OUTPUTS

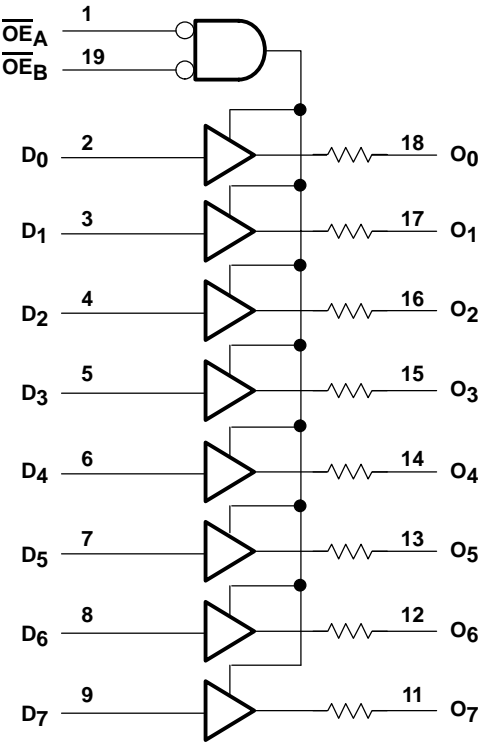
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FUNCTION TABLE

INPUTS			OUTPUT
$\overline{OE}_A$	$\overline{OE}_B$	D	
L	L	L	L
L	L	H	H
H	H	X	Z

H = High logic level, L = Low logic level,  
X = Don't care, Z = High-impedance state

logic diagram (positive logic)



absolute maximum rating over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1): Q package	68°C/W
SO package	58°C/W
Ambient temperature range with power applied, $T_A$	–65°C to 135°C
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JEDEC 51-7.



**CY74FCT2541T**  
**8-BIT BUFFER/LINE DRIVER**  
**WITH 3-STATE OUTPUTS**

SCCS041B – SEPTEMBER 1994 – REVISED SEPTEMBER 2001

**recommended operating conditions (see Note 2)**

		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>OH</sub>	High-level output current			–15	mA
I <sub>OL</sub>	Low-level output current			12	mA
T <sub>A</sub>	Operating free-air temperature	–40		85	°C

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.



# CY74FCT2541T

## 8-BIT BUFFER/LINE DRIVER

### WITH 3-STATE OUTPUTS

SCCS041B – SEPTEMBER 1994 – REVISED SEPTEMBER 2001

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V <sub>IK</sub>	V <sub>CC</sub> = 4.75 V,	I <sub>IN</sub> = −18 mA		−0.7	−1.2	V	
V <sub>OH</sub>	V <sub>CC</sub> = 4.75 V,	I <sub>OH</sub> = −15 mA	2.4	3.3		V	
V <sub>OL</sub>	V <sub>CC</sub> = 4.75 V,	I <sub>OL</sub> = 12 mA		0.3	0.55	V	
R <sub>out</sub>	V <sub>CC</sub> = 4.75 V,	I <sub>OL</sub> = 12 mA	20	25	40	Ω	
V <sub>hys</sub>	All inputs			0.2		V	
I <sub>I</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = V <sub>CC</sub>			5	μA	
I <sub>IH</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 2.7 V			±1	μA	
I <sub>IL</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 0.5 V			±1	μA	
I <sub>OZH</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 2.7 V			15	μA	
I <sub>OZL</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 0.5 V			−15	μA	
I <sub>OS</sub> ‡	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 0 V	−60	−120	−225	mA	
I <sub>off</sub>	V <sub>CC</sub> = 0 V,	V <sub>OUT</sub> = 4.5 V			±1	μA	
I <sub>CC</sub>	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> ≤ 0.2 V, V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V		0.1	0.2	mA	
ΔI <sub>CC</sub>	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 3.4 V§, f <sub>1</sub> = 0, Outputs open			0.5	2	mA	
I <sub>CCD</sub> ¶	V <sub>CC</sub> = 5.25 V at 50% duty cycle, Outputs open, One bit switching, $\overline{OE}_A = \overline{OE}_B = \text{GND}$ , V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V			0.06	0.12	mA/MHz	
I <sub>C</sub> <sup>#</sup>	V <sub>CC</sub> = 5.25 V, Outputs open, $\overline{OE}_A = \overline{OE}_B = \text{GND}$	One bit switching at f <sub>1</sub> = 10 MHz, at 50% duty cycle	V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V		0.7	1.4	mA
			V <sub>IN</sub> = 3.4 V or GND		1	2.4	
		Eight bits switching at f <sub>1</sub> = 2.5 MHz, at 50% duty cycle	V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V		1.3	2.6	
			V <sub>IN</sub> = 3.4 V or GND		3.3	10.6	
C <sub>i</sub>				5	10	pF	
C <sub>o</sub>				9	12	pF	

† Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests,  $I_{OS}$  tests should be performed last.

§ Per TTL-driven input ( $V_{IN} = 3.4 \text{ V}$ ); all other inputs at  $V_{CC}$  or GND

¶ This parameter is derived for use in total power-supply calculations.

#  $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

$I_C$  = Total supply current

$I_{CC}$  = Power-supply current with CMOS input levels

$\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4 \text{ V}$ )

$D_H$  = Duty cycle for TTL inputs high

$N_T$  = Number of TTL inputs at  $D_H$

$I_{CCD}$  = Dynamic current caused by an input transition pair (HLH or LHL)

$f_0$  = Clock frequency for registered devices, otherwise zero

$f_1$  = Input signal frequency

$N_1$  = Number of inputs changing at  $f_1$

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the  $I_{CC}$  formula.



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**CY74FCT2541T**  
**8-BIT BUFFER/LINE DRIVER**  
**WITH 3-STATE OUTPUTS**

SCCS041B – SEPTEMBER 1994 – REVISED SEPTEMBER 2001

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT2541T		CY74FCT2541AT		CY74FCT2541CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	D	O	1.5	8	1.5	4.8	1.5	4.1	ns
t <sub>PHL</sub>			1.5	8	1.5	4.8	1.5	4.1	
t <sub>PZH</sub>	$\overline{OE}$	O	1.5	10	1.5	6.2	1.5	5.8	ns
t <sub>PZL</sub>			1.5	10	1.5	6.2	1.5	5.8	
t <sub>PHZ</sub>	$\overline{OE}$	O	1.5	9.5	1.5	5.6	1.5	5.2	ns
t <sub>PLZ</sub>			1.5	9.5	1.5	5.6	1.5	5.2	



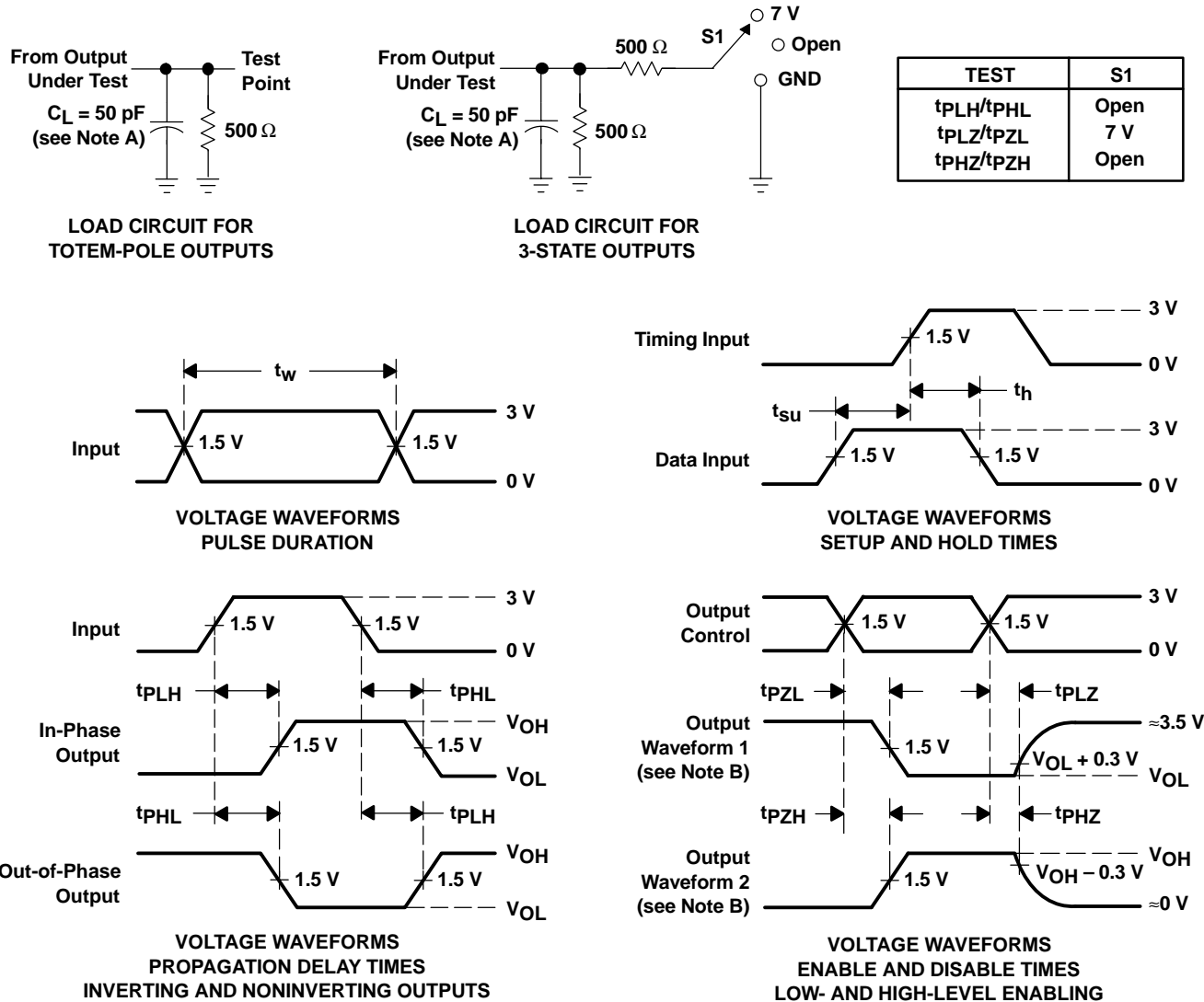
# CY74FCT2541T

## 8-BIT BUFFER/LINE DRIVER

### WITH 3-STATE OUTPUTS

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#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">CY74FCT2541ATQCT</a>	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541A
CY74FCT2541ATQCT.B	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541A
CY74FCT2541ATQCTG4	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541A
CY74FCT2541ATQCTG4.B	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541A
<a href="#">CY74FCT2541ATSOC</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541A
CY74FCT2541ATSOC.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541A
<a href="#">CY74FCT2541CTQCT</a>	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541C
CY74FCT2541CTQCT.B	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541C
<a href="#">CY74FCT2541CTSOC</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541C
CY74FCT2541CTSOC.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541C
<a href="#">CY74FCT2541TQCT</a>	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541
CY74FCT2541TQCT.B	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541
CY74FCT2541TQCTE4	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541
CY74FCT2541TQCTG4	Active	Production	SSOP (DBQ)   20	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2541
<a href="#">CY74FCT2541TSOC</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541
CY74FCT2541TSOC.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541
CY74FCT2541TSOCE4	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541
<a href="#">CY74FCT2541TSOCT</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541
CY74FCT2541TSOCT.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2541

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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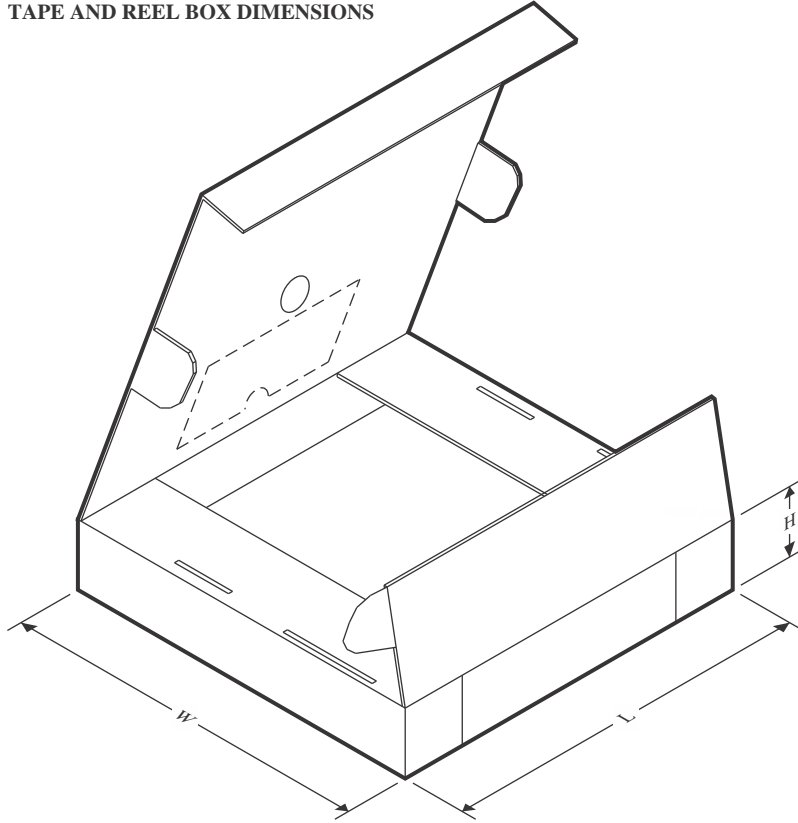
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT2541ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2541ATQCTG4	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2541CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2541TQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2541TSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT2541ATQCT	SSOP	DBQ	20	2500	353.0	353.0	32.0
CY74FCT2541ATQCTG4	SSOP	DBQ	20	2500	353.0	353.0	32.0
CY74FCT2541CTQCT	SSOP	DBQ	20	2500	353.0	353.0	32.0
CY74FCT2541TQCT	SSOP	DBQ	20	2500	353.0	353.0	32.0
CY74FCT2541TSOCT	SOIC	DW	20	2000	356.0	356.0	45.0

## TUBE

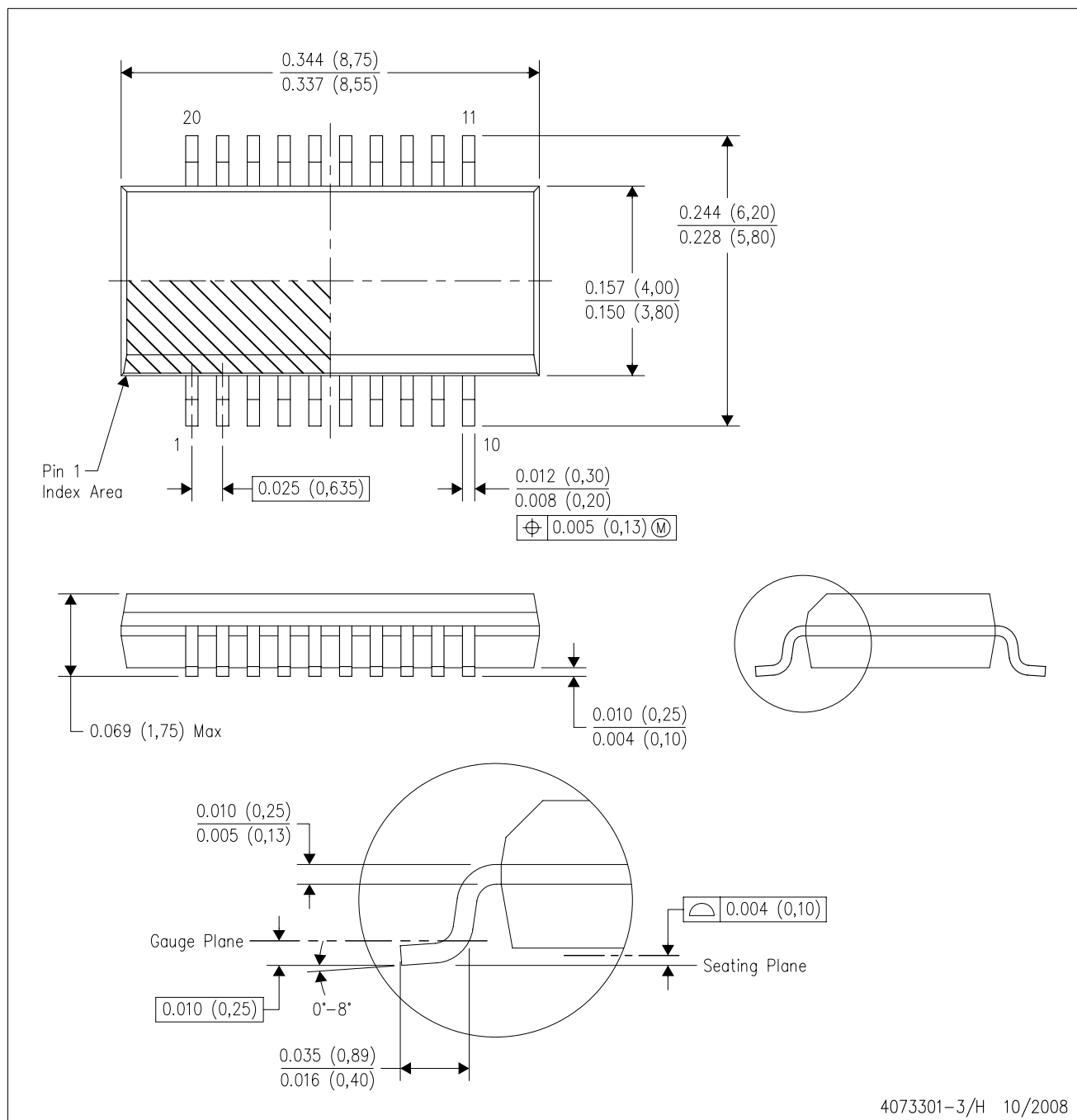


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CY74FCT2541ATSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT2541ATSOC.B	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT2541CTSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT2541CTSOC.B	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT2541TSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT2541TSOC.B	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT2541TSOCE4	DW	SOIC	20	25	507	12.83	5080	6.6

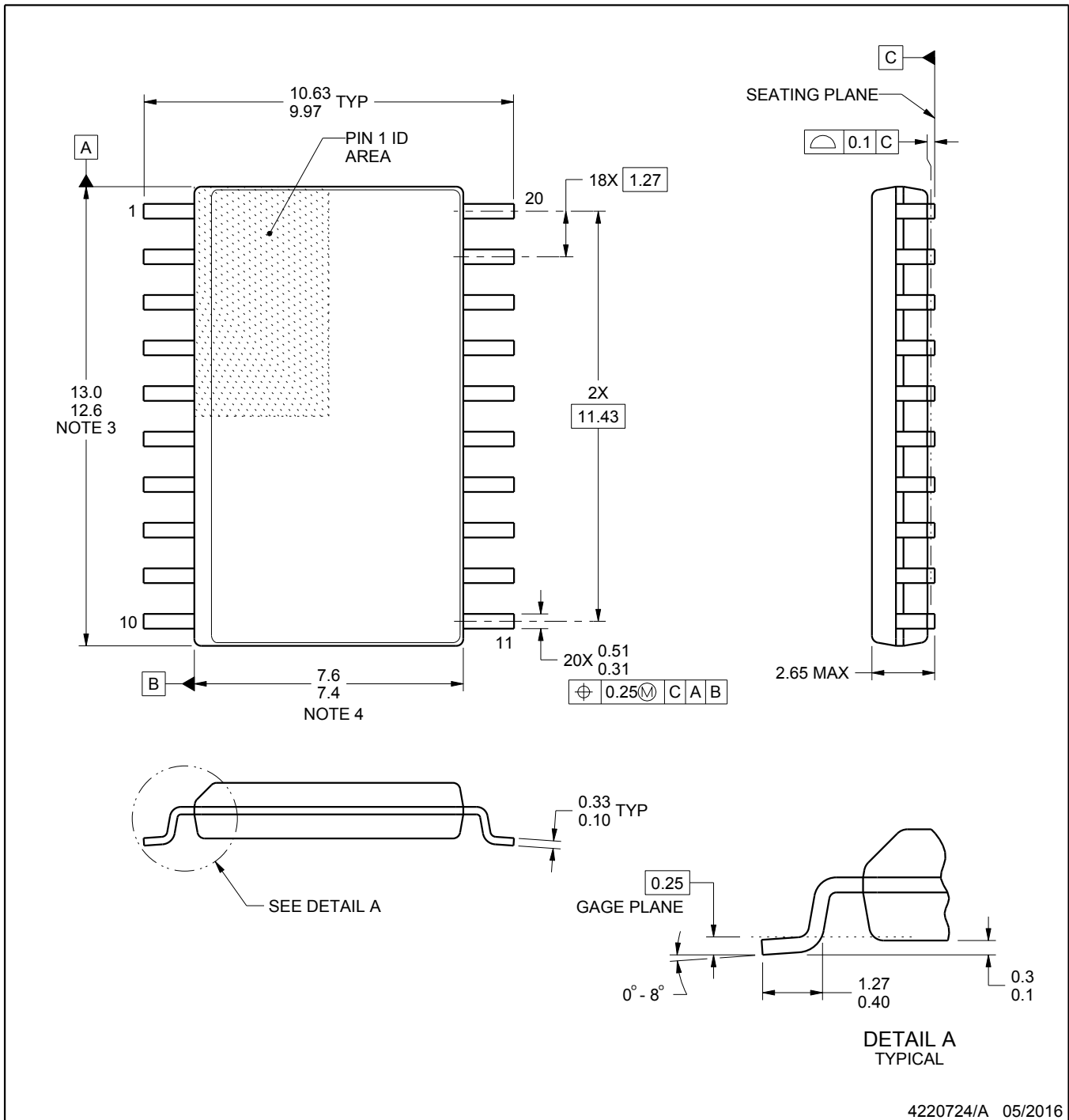
DBQ (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



4073301-3/H 10/2008

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AD.



## NOTES:

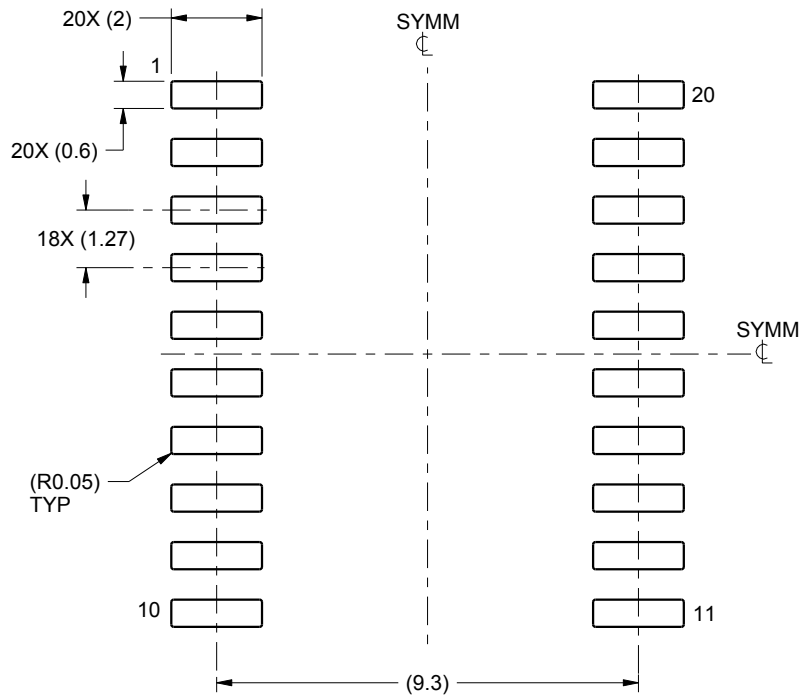
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

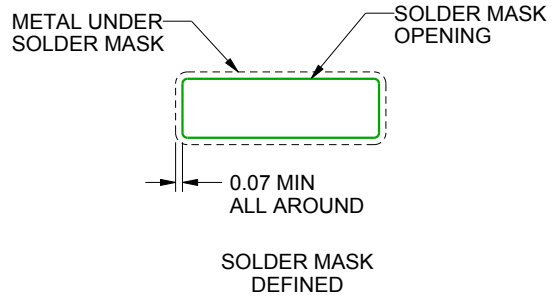
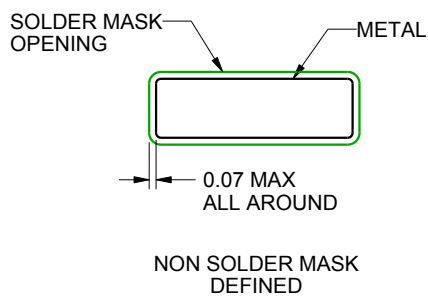
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

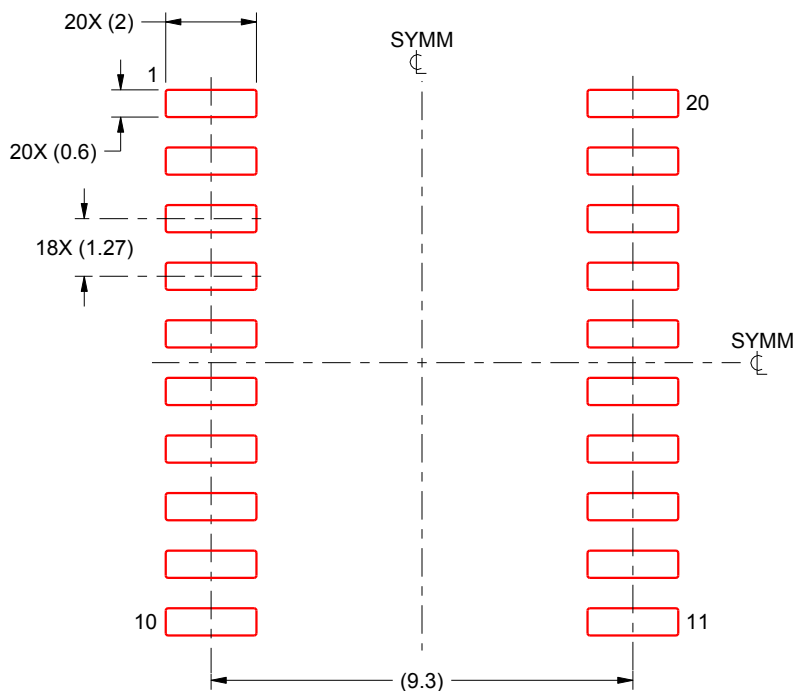
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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